UC1835 UC1836 UC2835 UC2836 UC3835 UC3836

High Efficiency Regulator Controller

FEATURES

- Complete Control for a High Current, Low Dropout, Linear Regulator
- Fixed 5V or Adjustable Output Voltage
- Accurate 2.5A Current Limiting with Foldback
- Internal Current Sense Resistor
- Remote Sense for Improved Load Regulation
- External Shutdown
- Under-Voltage Lockout and Reverse Voltage Protection
- Thermal Shutdown Protection
- 8 Pin Mini-Dip Package (Surface Mount also Available)

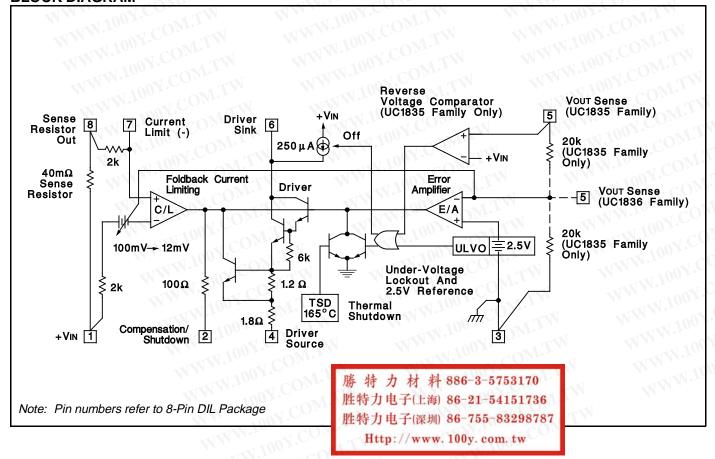
DESCRIPTION

The UC1835/6 families of linear controllers are optimized for the design of low cost, low dropout, linear regulators. Using an external pass element, dropout voltages of less than 0.5V are readily obtained. These devices contain a high gain error amplifier, a 250mA output driver, and a precision reference. In addition, current sense with foldback provides for a 2.5A peak output current dropping to less than 0.5A at short circuit.

These devices are available in fixed, 5V, (UC1835), or adjustable, (UC1836), versions. In the fixed 5 volt version, the only external parts required are an external pass element, an output capacitor, and a compensation capacitor. On the adjustable version the output voltage can be set anywhere from 2.5V to 35V with two external resistors.

Additional features of these devices include under-voltage lockout for predictable start-up, thermal shutdown and short circuit current limiting to protect the driver device. On the fixed voltage version, a reverse voltage comparator minimizes reverse load current in the event of a negative input to output differential.

BLOCK DIAGRAM



UC1835 UC1836 UC2835 UC2836 UC3835 UC3836

ABSOLUTE MAXIMUM RATINGS (Note 1)

Input Supply Voltage (+VIN)1.0V to + 40V
Driver Output Current (Sink or Source) 600mA
Driver Source to Sink Voltage + 40V
Maximum Current Through Sense Resistor4A
Vout Sense Input Voltage3V to + 40V
Power Dissipation at TA = 25°C (Note 2) 1000mW
Power Dissipation at Tc = 25°C (Note 2) 2000mW

Operating Junction Temperature55°C to +150°C
Storage Temperature65°C to +150°C
Lead Temperature (Soldering, 10 Seconds) 300°C
Note 1: Voltages are referenced to ground, (Pin 3). Currents are
positive into, negative out of, the specified terminals.
Consult Packaging Section of Databook for thermal

considerations and limitations of packages.

CONNECTION DIAGRAMS

+Vin 1	8 Sense Resistor Out
Compensation/ 2	7 Current Limit (-)
Ground 3	6 Driver Sink
Driver Source 4	5 Vout Sense

SOIC-16 (TOP DW Package	V.COM.	
N/C	1	16 N/C
+VIN	2	5 Sense Resistor Out
+Vin	3	14 Sense Resistor Out
Compensation/ Shutdown	4	13 Current Limit (-)
N/C	5	12 N/C
Ground	6	11 Driver Sink
N/C	7	10 N/C
Driver Source	8	9 Vout Sense

OP VIEW)	PACKAGE PIN FUNCT	ΓΙΟΝ
, L Packages	FUNCTION	PIN
	N/C	1
	+VIN	2
	+VIN	3
3 2 1 20 19	N/C	4
4 18	Compensation/ Shutdown	5
5 17	N/C	6
6 16	Ground	7
7 15	N/C	8
8 14	N/C	9
9 10 11 12 13	Driver Source	10
	N/C	11
	Vout Sense	12
	N/C	13
	N/C	14
	Driver Sink	15
	N/C	16
	Current Limit (-)	17
	N/C	18
	Sense Resistor Out	19
	Sense Resistor Out	20

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, specifications hold for $TA = 0^{\circ}C$ to $+ 70^{\circ}C$ for the UC3835/6, $-25^{\circ}C$ to $+ 85^{\circ}C$ for the UC2835/6, and $-55^{\circ}C$ to $+ 125^{\circ}C$ for the UC1835/6, +VIN = 6V, Driver Source= 0V, Driver Sink = 5V, TA = TJ.

PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input Supply	THE WINN CONT. CO.	W	WW	1	O.Y.C.
Supply Current	+VIN = 6V	-XX	2.75	4.0	mA
	+VIN = 40V	7.	3.75	6.0	mA
UVLO Threshold	+VIN Low to High, VOUT Sense = 0V	3.9	4.4	4.9	V
Threshold Hysteresis	COM. TIMW. TO Y. COM	TW	0.1	0.35	V
Reverse Current	+VIN = -1.0V, Driver Sink Open	MIL	6.0	20	mA
Regulating Voltage and Error Amplifier (UC	C1835 Family Only)	MIN		M.	TN 10
Regulating Level at Vout Sense (VREG)	Driver Current = 10mA, TJ = 25°C	4.94	5.0	5.06	V
WW.100	Over Temperature	4.9	N	5.1	V
Line Regulation	+VIN = 5.2V + 35V	COM'I	15	40	mV
Load Regulation	Driver Current = 0 to 250mA		6.0	25	mV
Bias Current at Vout Sense	Vout Sense = 5.0V	75	125	210	μΑ
Error Amp Transconductance	±100μA at Compensation/Shutdown Pin	0.8	1.3	2.0	mS
Maximum Compensation Output Current	Sink or Source, Driver Source Open	90	200	260	μΑ

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UC1835 **UC1836 UC2836 UC2835 UC3835 UC3836**

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, specifications hold for TA = 0°C to + 70°C for the UC3835/6, -25°C to + 85°C for the UC2835/6, and -55°C to +125°C for the UC1835/6, +VIN = 6V, Driver Source= 0V, Driver Sink = 5V, TA = TJ.

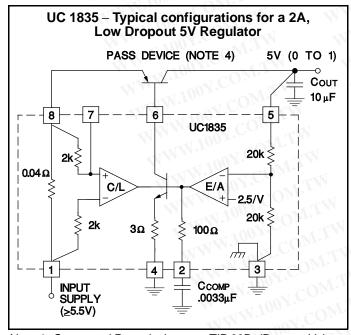
PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Regulating Voltage and Error Amplifier (UC	1836 Family Only)	TW			
Regulating Level at Vout Sense (VREG)	Driver Current = 10mA, T _J = 25°C	2.47	2.5	2.53	V
	Over Temperature	2.45		2.55	V
Line Regulation	+VIN = 5.2V to 35V	MIN	6.0	20	mV
Load Regulation	Driver Current = 0 to 250mA	WT	3.0	15	mV
Bias Current at Vout Sense	Vout Sense =2.5V	-1.0	-0.2		μΑ
Error Amp Transconductance	±100μA at Compensation/Shutdown Pin	0.8	1.3	2.0	mS
Maximum Compensation Output Current	Sink or Source, Driver Source Open	90	200	260	μΑ
Driver	COM.	COMP	TW		
Maximum Current	On COWITH.	250	500		mA
Saturation Voltage	Driver Current = 250mA, Driver Sink	Y.	2.0	2.8	V
Pull-Up Current at Driver Sink	Compensation/Shutdown=0.45V	140	250	300	μΑ
Driver Sink Leakage	In UVLO	N CO	VI	10	μΑ
WI 100Y.COMITIN WWW.	In Reverse Voltage (UC1835 Family Only)	01, 2.	M_{II}	10	μΑ
Thermal Shutdown	WW.	1001.0	165		°C
Foldback Current Limit	MAIN COMP.	N.C	Oh	TW	9
Current Limit Levels at Sense Resistor Out	Vout Sense = (0.99) VREG	2.2	2.5	2.8	Α
	Vout Sense = (0.5) VREG	1.3	1.5	1.7	Α
MW.IO. COM.	Vout Sense = 0V	0.25	0.4	0.55	Α
Current Limit Amp Tansconductance	±100μA at Compensation/Shutdown, Vout Sense = (0.9) VREG	12	24	42	mS
Limiting Voltage at Current Limit (-) (Note 2)	Vout Sense = (0.9) VREG Volts Below +VIN, TJ = 25°C	80	100	140	mV
Sense Resistor Value (Note 3)	V _{OUT} Sense = (0.9) V _{REG} , I _{OUT} = I _A , T _J = 25°C	WW.	40	CO_{M}	mΩ

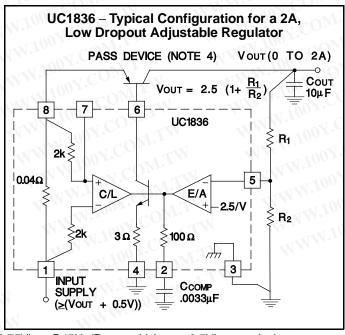
Note 2: This voltage has a positive temperature coefficient of approximately 3500ppm/°C.

Note 3: This resistance has a positive temperature coefficient of approximately 3500ppm/°C.

The total resistance from Pin 1 to Pin 8 will include an additional 60 to $100m\Omega$ of package resistance.

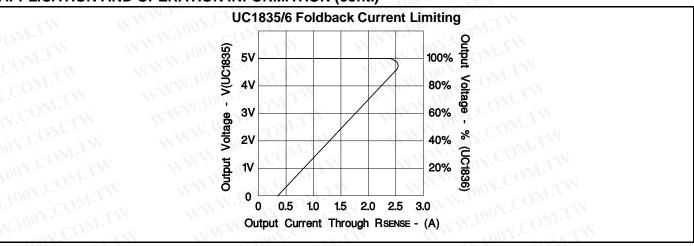
APPLICATION AND OPERATION INFORMATION





Note 4: Suggested Pass devices are TIP 32B. (Dropout Voltage ≤0.75V) or, D45H, (Dropout Voltage ≤0.5V), or equivalents.

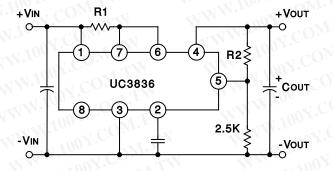
APPLICATION AND OPERATION INFORMATION (cont.)



UC3835/36 TYPICAL APPLICATIONS

Low Current Application

using the UC3836 internal drive transistor



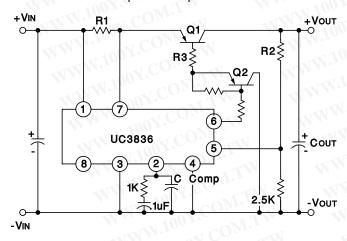
Typical Output Current vs VIN and Vouт

of the UC3836 internal drive transistor for PDISS = 0.5W (approx.)

	- 1	NW		Vin	C	- N	TV
* I	Volts	5	9	12	15	18	24
M	2	150	60	40	30	20	12
Vоит	5	11	105	55	35	25	15
. 44.	9	4	211	130	60	35	20
TV	12	1	NW	* '	120	55	25
	15	Cui	rent	in m	Α	110	30

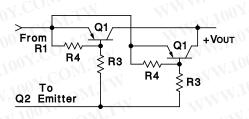
High Current Application

using drive transistor Q2 to increase Q1 base drive and reduce UC3836 power dissipation



Parallel Pass Transistors

can be added for high current or high power dissipation applications



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EQUATIONS:

 $R_1 = 0.100 \text{ V/Iout (MAX)}$

 $R_2 = (VOUT - 2.5V/1mA)$

R3 = ((VIN - VBE - VSAT)*BETA(min))/IOUT (max)





18-Sep-2008



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finisl	n MSL Peak Temp ⁽³⁾
5962-9065002PA	ACTIVE	CDIP	JG	8	11	TBD	A42 SNPB	N / A for Pkg Type
UC1835J	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UC1835J883B	OBSOLETE	CDIP	JG	8	MAA	TBD	Call TI	Call TI
UC1835L883B	OBSOLETE	LCCC	FK	20	WW.	TBD	Call TI	Call TI
UC1836J	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
UC1836J883B	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
UC1836L	OBSOLETE	TO/SOT	LTV	20	W	TBD	Call TI	Call TI
UC1836L883B	OBSOLETE	TO/SOT	COLL	20	V	TBD	Call TI	Call TI
UC2835D	ACTIVE	SOIC	CODV	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2835DG4	ACTIVE	SOIC	Y.CD	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2835J	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UC2835N	ACTIVE	PDIP	POT	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2835NG4	ACTIVE	PDIP	100 P.	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2836D	ACTIVE	SOIC	10D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DG4	ACTIVE	SOIC	V. D	C 8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DW	OBSOLETE	SOIC	DW	16	IA.	TBD (Call TI	Call TI
UC3835N	ACTIVE	PDIP	P. I	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3835NG4	ACTIVE	PDIP	Р	8.00	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3836D	ACTIVE	SOIC	D	108	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3836NG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

PACKAGE OPTION ADDENDUM



18-Sep-2008

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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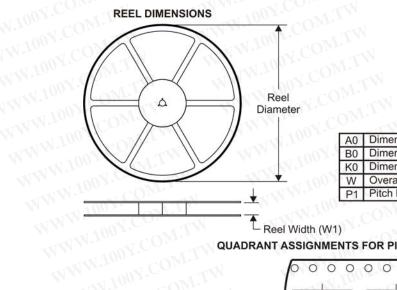
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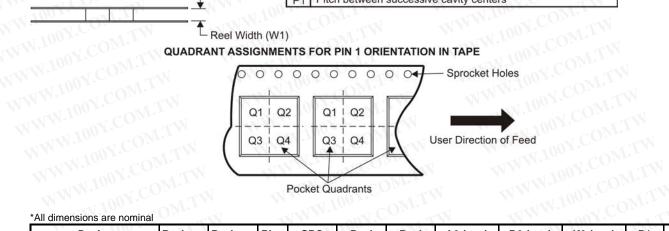


TAPE AND REEL INFORMATION



TAPE DIMENSIONS **←** K0 **←** 0 $\Phi \Phi \Phi \Phi$ 0 Φ 0 0 B₀ → A0 ← Cavity

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers



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ensions are nomina Device		Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadran
JC3836DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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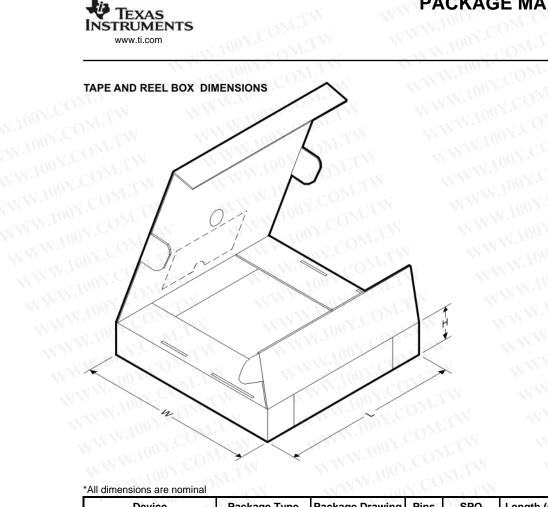
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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm
UC3836DTR	SOIC	D. 1	8	2500	346.0	346.0	29.0

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